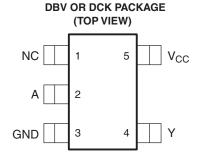
SCES674-MARCH 2007

#### **FEATURES**

- Controlled Baseline
  - One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of –55°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree (1)
- Supports 5-V V<sub>CC</sub> Operation
- Inputs Accept Voltages to 5.5 V
- Max t<sub>pd</sub> of 4.6 ns at 3.3 V
- Low Power Consumption, 10-μA Max I<sub>CC</sub>
- ±24-mA Output Drive at 3.3 V
- I<sub>off</sub> Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per
- (1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

#### JESD 78, Class II

- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)



#### DESCRIPTION/ORDERING INFORMATION

This single Schmitt-trigger inverter is designed for 1.65-V to 5.5-V V<sub>CC</sub> operation.

The SN74LVC1G14 device contains one inverter and performs the Boolean function  $Y = \overline{A}$ . The device functions as an independent inverter, but because of Schmitt action, it may have different input threshold levels for positive-going  $(V_{T_n})$  and negative-going  $(V_{T_n})$  signals.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

### ORDERING INFORMATION

T <sub>A</sub>	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING <sup>(2)</sup>
SOT (SOT-23) – DBV		Reel of 3000	SN74LVC1G14MDBVREP	SBLM
-55 C to 125 C	-55°C to 125°C SOP – DCK		SN74LVC1G14MDCKREP	CAL

<sup>(1)</sup> For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI Web site at www.ti.com.

(2) DBV/DCK: The actual top-side marking has one additional character that designates the assembly/test site.

#### **FUNCTION TABLE**

INPUT A	OUTPUT Y
Н	L
L	Н



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



### **LOGIC DIAGRAM (POSITIVE LOGIC)**



## Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CC}$	V <sub>CC</sub> Supply voltage range				V
VI	Input voltage range (2)		-0.5	6.5	V
Vo	Voltage range applied to any output in the high-imp	pedance or power-off state <sup>(2)</sup>	-0.5	6.5	V
Vo	Vo Voltage range applied to any output in the high or low state (2)(3)				V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0		-50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA
Io	Continuous output current			±50	mA
	Continuous current through V <sub>CC</sub> or GND			±100	mA
0	Package thermal impedance <sup>(4)</sup>			389	°C/W
$\theta_{JA}$	DBV				C/VV
$T_{\text{stg}}$	T <sub>stg</sub> Storage temperature range				°C

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

The value of V<sub>CC</sub> is provided in the recommended operating conditions table.

(4) The package thermal impedance is calculated in accordance with JESD 51-2.

# Recommended Operating Conditions<sup>(1)</sup>

			MIN	MAX	UNIT
1/	Cumply veltage	Operating	1.65	5.5	V
$V_{CC}$	Supply voltage	Data retention only	1.5		V
VI	Input voltage		0	5.5	V
Vo	Output voltage		0	V <sub>CC</sub>	V
		V <sub>CC</sub> = 1.65 V		-4	
		V <sub>CC</sub> = 2.3 V		-8	
$I_{OH}$	OH High-level output current	V 2.V		-16	
		V <sub>CC</sub> = 3 V		-24	
		V <sub>CC</sub> = 4.5 V		-32	
		V <sub>CC</sub> = 1.65 V		4	
		V <sub>CC</sub> = 2.3 V		8	
$I_{OL}$	Low-level output current	V 2 V		16	mA
		V <sub>CC</sub> = 3 V		24	
		V <sub>CC</sub> = 4.5 V		32	
T <sub>A</sub>	Operating free-air temperature		-55	125	°C

(1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



## **Electrical Characteristics**

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>cc</sub>	MIN	TYP <sup>(1)</sup> MAX	UNIT	
		1.65 V	0.79	1.16		
$V_{T+}$		2.3 V	1.11	1.56		
Positive-going input threshold		3 V	1.5	1.87	V	
voltage		4.5 V	2.16	2.74		
		5.5 V	2.61	3.33		
		1.65 V	0.39	0.62		
$V_{T-}$		2.3 V	0.58	0.87		
Negative-going input threshold		3 V	0.84	1.14	V	
voltage		4.5 V	1.41	1.79		
		5.5 V	1.87	2.29		
		1.65 V	0.37	0.62		
$\Delta V_T$		2.3 V	0.48	0.77		
Hysteresis (V <sub>T+</sub> - V <sub>T-</sub> )		3 V	0.56	0.87	V	
		4.5 V	0.71	1.04		
		5.5 V	0.71	1.11		
	$I_{OL} = -100 \mu A$	1.65 V to 4.5 V	V <sub>CC</sub> - 0.1			
	$I_{OL} = -4 \text{ mA}$	1.65 V	1.2			
V	$I_{OL} = -8 \text{ mA}$	2.3 V	1.9		V	
$V_{OH}$	$I_{OL} = -16 \text{ mA}$	3 V	2.4		V	
	$I_{OL} = -24 \text{ mA}$	3 V	2.3			
	$I_{OL} = -32 \text{ mA}$	4.5 V	3.8			
	$I_{OL} = 100 \mu\text{A}$	1.65 V to 4.5 V		0.1		
	$I_{OL} = 4 \text{ mA}$	1.65 V		0.45		
V	$I_{OL} = 8 \text{ mA}$	2.3 V		0.3	V	
$V_{OL}$	I <sub>OL</sub> = 16 mA	3 V		0.4	V	
	I <sub>OL</sub> = 24 mA	3 V		0.55		
	I <sub>OL</sub> = 32 mA	4.5 V		0.55	İ	
I <sub>I</sub> A input	$V_I = 5.5 \text{ V or GND}$	0 to 5.5 V		±5	μΑ	
I <sub>off</sub>	$V_I$ or $V_O = 5.5 \text{ V}$	0		±10	μΑ	
I <sub>CC</sub>	$V_I = 5.5 \text{ V or GND}, \qquad I_O = 0$	1.65 V to 5.5 V		19	μΑ	
$\Delta I_{\text{CC}}$	One input at $V_{CC} - 0.6 \text{ V}$ , Other inputs at $V_{CC}$ or GND	3 V to 5.5 V		500	μΑ	
C <sub>i</sub>	$V_I = V_{CC}$ or GND	3.3 V		4.5	pF	

<sup>(1)</sup> All typical values are at  $V_{CC}$  = 3.3 V,  $T_A$  = 25°C.

## **Switching Characteristics**

over recommended operating free-air temperature range,  $C_L = 15 \text{ pF}$  (unless otherwise noted) (see Figure 1)

PARAMETER	PARAMETER FROM (INPUT)		V <sub>CC</sub> = 1.8 V ± 0.15 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		V <sub>CC</sub> = 5 V ± 0.5 V		UNIT
	(INFOT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	Α	Υ	2.8	9.9	1.6	5.5	1.5	4.6	0.9	4.4	ns

# SN74LVC1G14-EP SINGLE SCHMITT-TRIGGER INVERTER

SCES674-MARCH 2007



## **Switching Characteristics**

over recommended operating free-air temperature range,  $C_L = 30 \text{ pF}$  or 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = ± 0.1		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		V <sub>CC</sub> = 5 V ± 0.5 V		UNIT
	(INPOT)	(001701)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	Α	Υ	3.8	16	2	7.5	1.8	6.0	1.2	5	ns

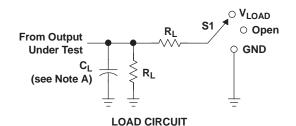
# **Operating Characteristics**

 $T_A = 25^{\circ \circ}C$ 

PARAMETER	TEST CONDITIONS	V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> = 2.5 V	V <sub>CC</sub> = 3.3 V V <sub>CC</sub> = 5 V		UNIT	
TAKAMETEK	1231 CONDITIONS	TYP	TYP	TYP	TYP	ONII	
C <sub>pd</sub> Power dissipation capacitance	f = 10 MHz	20	21	22	25	pF	

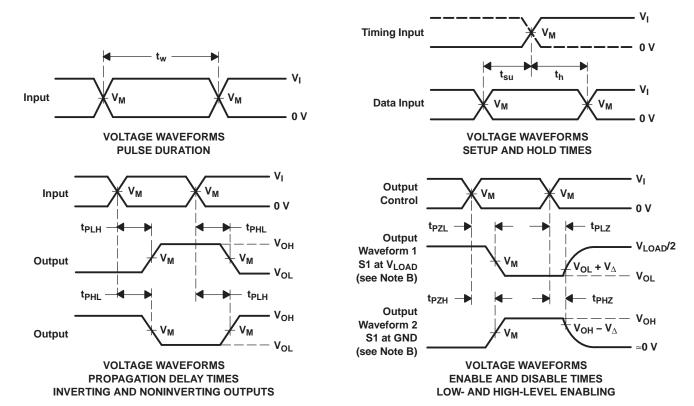


### PARAMETER MEASUREMENT INFORMATION



TEST	S1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	$V_{LOAD}$
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

.,	IN	PUTS	.,	.,	•	_	.,
V <sub>CC</sub>	VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	V <sub>LOAD</sub>	CL	R <sub>L</sub>	$V_{\Delta}$
1.8 V ± 0.15 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	15 pF	<b>1 M</b> Ω	0.15 V
2.5 V $\pm$ 0.2 V	$V_{CC}$	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	15 pF	<b>1 M</b> Ω	0.15 V
3.3 V $\pm$ 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	15 pF	<b>1 M</b> Ω	0.3 V
5 V $\pm$ 0.5 V	$v_{cc}$	≤2.5 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	15 pF	<b>1 M</b> Ω	0.3 V

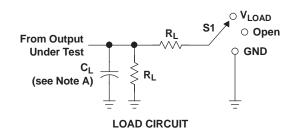


- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_0$  = 50  $\Omega$ .
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
  - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

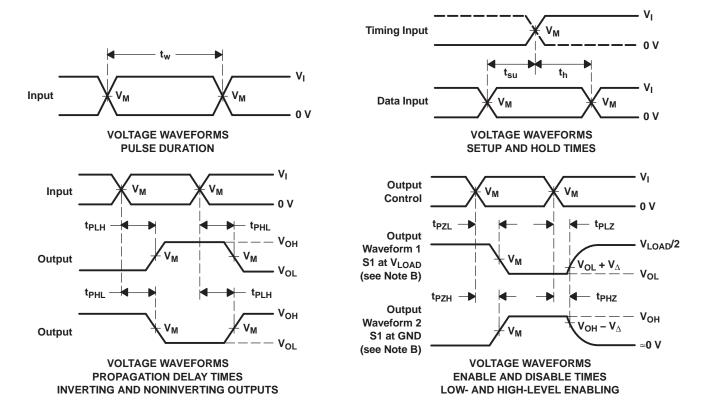


### PARAMETER MEASUREMENT INFORMATION



TEST	S1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	V <sub>LOAD</sub>
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

V	INF	PUTS	.,	V	_	Б	V
V <sub>CC</sub>	VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	V <sub>LOAD</sub>	CL	R <sub>L</sub>	$V_{\Delta}$
1.8 V ± 0.15 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	30 pF	<b>1 k</b> Ω	0.15 V
2.5 V $\pm$ 0.2 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	30 pF	500 Ω	0.15 V
3.3 V $\pm$ 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
5 V $\pm$ 0.5 V	V <sub>CC</sub>	≤2.5 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	50 pF	500 Ω	0.3 V



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_0$  = 50  $\Omega$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- H. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms



## **PACKAGE OPTION ADDENDUM**

10-Dec-2020

#### PACKAGING INFORMATION

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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
1P1G14MDBVREPG4	ACTIVE	SOT-23	DBV	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	SBLM	Samples
SN74LVC1G14MDBVREP	ACTIVE	SOT-23	DBV	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	SBLM	Samples
V62/07626-01XE	ACTIVE	SOT-23	DBV	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	SBLM	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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## **PACKAGE OPTION ADDENDUM**

10-Dec-2020

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### OTHER QUALIFIED VERSIONS OF SN74LVC1G14-EP:

Automotive: SN74LVC1G14-Q1

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects

# PACKAGE MATERIALS INFORMATION

www.ti.com 3-Aug-2017

## TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

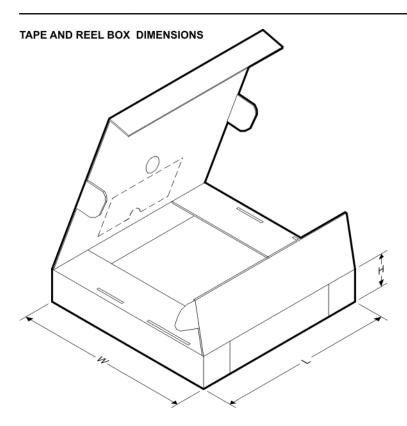
## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC1G14MDBVREP	SOT-23	DBV	5	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3

www.ti.com 3-Aug-2017



#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74LVC1G14MDBVREP	SOT-23	DBV	5	3000	202.0	201.0	28.0	



SMALL OUTLINE TRANSISTOR



#### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
  2. This drawing is subject to change without notice.
  3. Reference JEDEC MO-178.

- 4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
- 5. Support pin may differ or may not be present.



SMALL OUTLINE TRANSISTOR



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE TRANSISTOR



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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